1-13.130.01	le standarc							
	Operating temperature ra	-35°C to +85°C(No	-35°C to +85°C(Note 1) Storatemp		inge	-10°C to +60°C(1	Note 3)	
Rating	Operating humidity range	20 % to 80 % (Not		Storage humidity range		40 % to 70 %(Note 3)		
	Voltage	150 V AC (DC)		Current		1 A		
	Applicable	DF13-*DS-1.25	50	Applicable		DF13(G)-2630SCF		
Connector						DF13-3032S		
			cificatio	ons				-1
	tem	Test method			Rec	uirements	QT	A
Construc		<u></u>						<b>—</b>
General exar	mination	Visually and by measuring instrument.		Accordir	ng to drawing	].	Х	)
Marking		Confirmed visually.					Х	>
	characteris						X	-
		, , , , , , , , , , , , , , , , , , ,	0 m A (DC or 1000 Hz).		30 mΩ MAX.			
Insulation resistance		100 V DC.		500 MΩ MIN.			Х	-
Voltage proof 500		500 V AC for 1 min.	C for 1 min.		No flashover or breakdown.			-
	cal charac	teristics						
Mechanical operation		30 times insertions and extractions.			① Contact resistance: 30 m $\Omega$ MAX.			_
Vibration		Frequency 10 to 55 Hz, single amplitude			<ul> <li>② No damage, crack or looseness of parts.</li> <li>① No electrical discontinuity of 1μs.</li> <li>② No damage, crack or looseness of parts.</li> </ul>			+
VIDIAUUI		0.75 mm, at 2 h, for 3 directions.						-
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.						-
Environn	nental cha	racteristics						
Rapid chang		Temperature -55 $\rightarrow$ 15 to 35 $\rightarrow$ +85 $\rightarrow$ 15	5 to 35 °c	① Cont	act resistand	ce: 30mΩ MAX.		
Damp heat (Steady state)		Time $30 \rightarrow 2 \text{ to } 3 \rightarrow 30 \rightarrow 2 \text{ to } 3 \text{ min.}$ Under 5 cycles.			<ul> <li>② Insulation resistance: 500 MΩ MIN.</li> <li>③ No damage, crack or looseness of parts.</li> </ul>			-
		Exposed at 40 $\pm$ 2 °c, 90 to 95 %, 96 h.						-
Resistance to soldering heat		1) Reflow soldering			rmation of c	ase of excessive loosenes		
		<ul> <li>«Reflow area » 250°C MAX 10 sec MAX 230°C MIN 60 sec MAX &lt;</li></ul>		of the te			X	
		Soldered at solder temperature,	-		Solder shall cover a minimum of			_
Solderability				1 95 % 0	i the sufface	being immersed.		
Note 2:No cor Note 3:Apply t	S e the temperatur ndensing to the condition	245°c for insertion duration, 3sec. e rising by current. of long term storage for unused products befo perating temperature and humidity range is app		d,	ig transportati	on.		
Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	6 e the temperatur ndensing to the condition occb on board, op	e rising by current. of long term storage for unused products befo	plied for interin	d,	ig transportat	<sup>on.</sup>	Dat	te
Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	s e the temperatur ndensing to the condition pocb on board, op nt E	e rising by current. of long term storage for unused products befo perating temperature and humidity range is ap Description of revisions	plied for interin	n storage durir		Checked		
Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	s e the temperatur ndensing to the condition pocb on board, op nt E	e rising by current. of long term storage for unused products befo verating temperature and humidity range is ap	plied for interin	rd, n storage durir esigned	proved	Checked HS. OKAWA	Dat 16. 05.	
Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	s e the temperatur ndensing to the condition pocb on board, op nt E	e rising by current. of long term storage for unused products befo perating temperature and humidity range is ap Description of revisions	plied for interin	rd, n storage durir esigned App Ch	proved	Checked		. 16
Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	s e the temperatur ndensing to the condition pocb on board, op nt E	e rising by current. of long term storage for unused products befo perating temperature and humidity range is ap Description of revisions	plied for interin	rd, n storage durir esigned App Ch Des	proved ecked signed	Checked HS. OKAWA TS. FUKUSHIMA YK. YAMAGUCHI	16.05. 16.05. 16.05.	. 16 . 14 . 14
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Remarks Note 1:Include Note 2:No cor Note 3:Apply t after p	s e the temperatur ndensing to the condition of boot on board, op nt herwise spe	e rising by current. of long term storage for unused products befo perating temperature and humidity range is ap Description of revisions	plied for interin	rd, n storage durir esigned App Ch Des	proved ecked signed rawn	Checked HS. OKAWA TS. FUKUSHIMA YK. YAMAGUCHI	16. 05. 16. 05. 16. 05.	. 16 . 14 . 14 . 13
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